

ABSTRACT:

The semiconductor device (10) comprises a carrier (30) and a semiconductor element (20), such as an integrated circuit. The carrier (30) is provided with apertures (15), thereby defining connecting conductors (31-33) having side faces (3). Notches (16) are present in the side faces (3). The semiconductor element (20) is enclosed in an encapsulation (40) that extends into the notches (16) in the carrier (30). As a result, the encapsulation (40) is mechanically anchored in the carrier (30). The semiconductor device (10) can be made in a process wherein, after the encapsulating step, no lithographic steps are necessary.

Fig. 1